



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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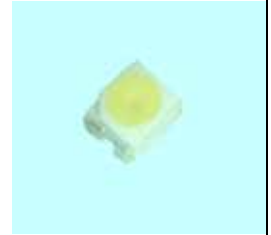
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



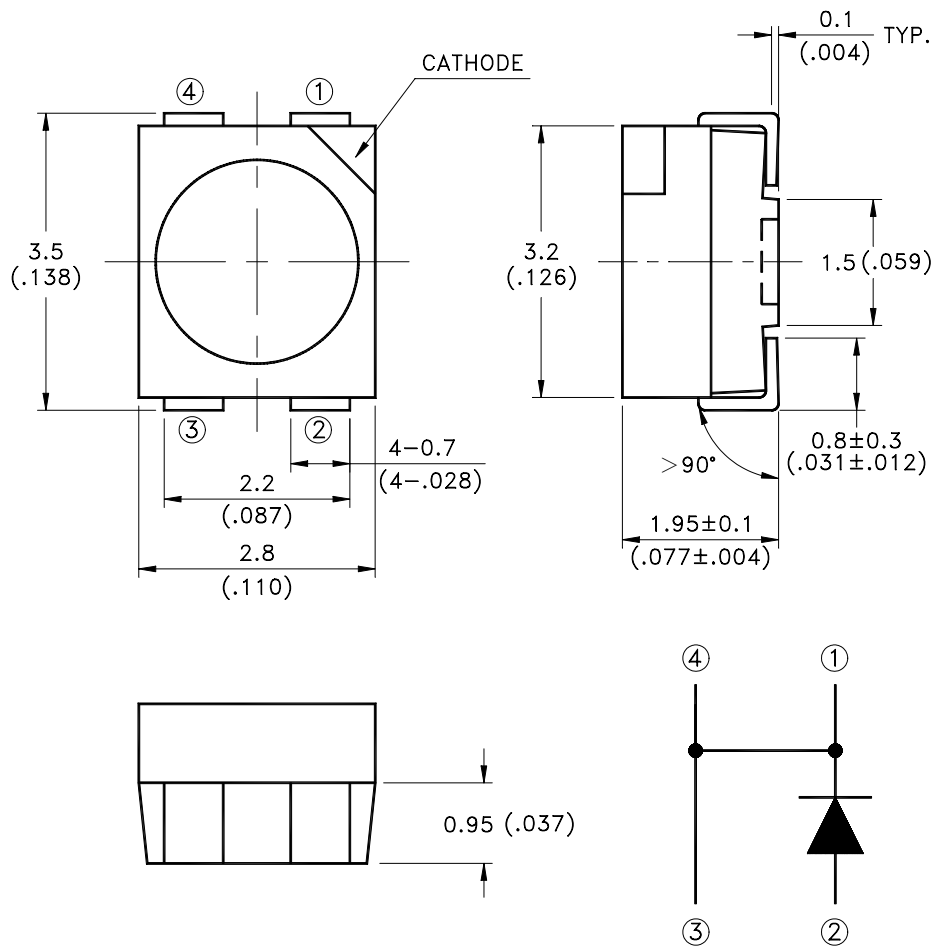
Property of Lite-On Only

Features

- * Package in 8mm tape on 7" diameter reels.
- * Compatible with automatic placement equipment.
- * Compatible with infrared and vapor phase reflow solder process.
- * EIA STD package.
- * I.C. compatible.
- * Lead Free Package(According to RoHS)



Package Dimensions



Part No.	Lens Color	Source Color
LTW-E670DS	Yellow	InGaN White

Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 mm (.008") unless otherwise noted.

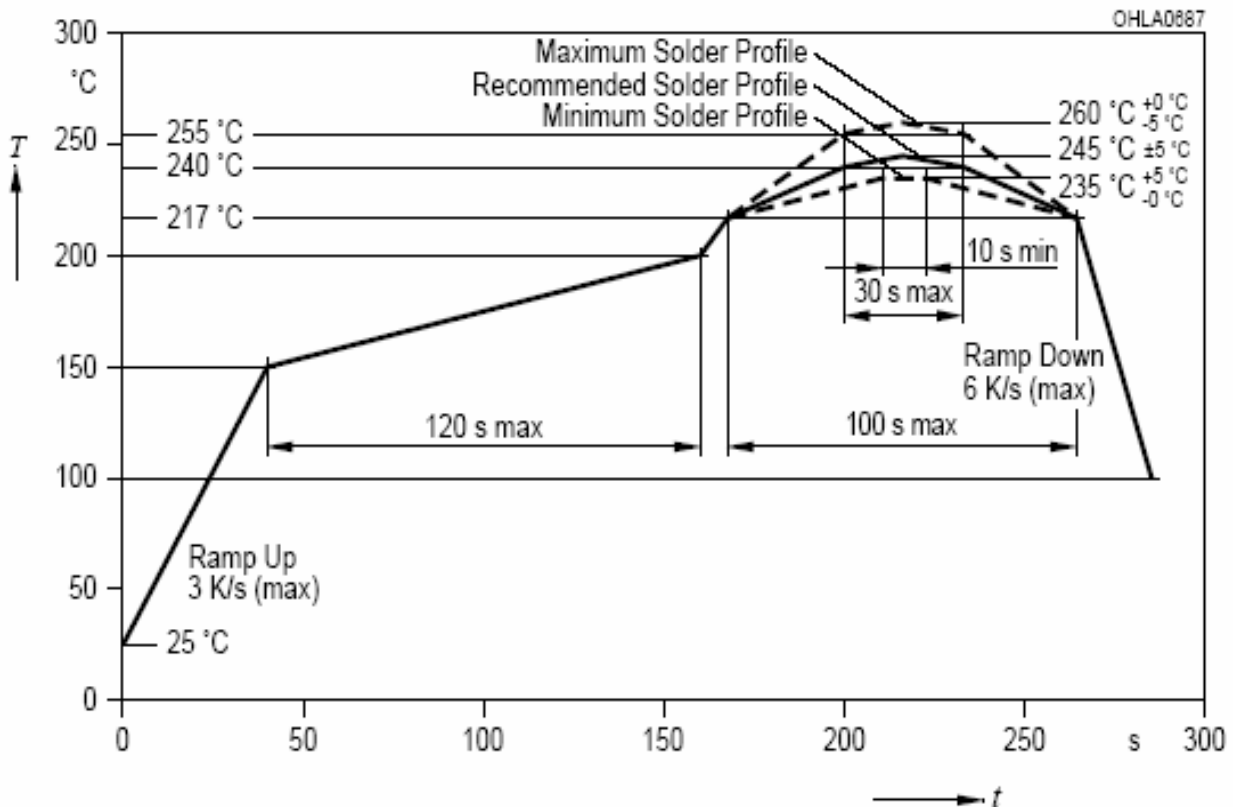
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Absolute Maximum Ratings at Ta=25°C

Parameter	LTW-E670DS	Unit
Power Dissipation	120	mW
Peak Forward Current (1/10 Duty Cycle, 0.1ms Pulse Width)	120	mA
DC Forward Current	80	mA
Reverse Voltage	5	V
Operating Temperature Range	-30°C to +85°C	
Storage Temperature Range	-40°C to +100°C	
Wave Soldering Condition	260°C For 5 Seconds	

Suggest IR Reflow Condition :

IR-Reflow Soldering Profile for lead free soldering (Acc. to J-STD-020B)



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Electrical Optical Characteristics At Ta=25°C

Parameter	Symbol	Part No. LTW-	Min.	Typ.	Max.	Unit	Test Condition
Luminous Intensity	IV	E670DS	2240.0		3550.0	mcd	IF = 50mA Note 1, 2, 5
Viewing Angle	2θ 1/2	E670DS		120		deg	Fig.6
Chromaticity Coordinates	x	E670DS		0.31			IF = 50mA Note 3, 5 Fig.1
	y			0.30			
Forward Voltage	VF	E670DS		3.7	4.5	V	IF = 50mA
Reverse Current	IR	E670DS			10	μA	VR = 5V

Note : 1. Luminous intensity is measured with a light sensor and filter combination that approximates the CIE eye-response curve.

2. Iv classification code is marked on each packing bag.

3. The chromaticity coordinates (x, y) is derived from the 1931 CIE chromaticity diagram.

4. Caution in ESD:

Static Electricity and surge damages the LED. It is recommended using a wrist band or anti-electrostatic glove when handling the LED. All devices, equipment and machinery must be properly grounded.

5. Tester

CAS140B is for the chromaticity coordinates (x, y) & IV.

6. The chromaticity coordinates (x, y) guarantee should be added ± 0.02 tolerance.

Property of Lite-On Only**Bin Code List**

IV Spec. Table

IV Bin	Luminous Intensity (mcd) at IF = 50mA	
	Min.	Max.
X2	2240.0	2800.0
Y1	2800.0	3550.0

Tolerance on each Luminous Intensity bin is +/- 15%.

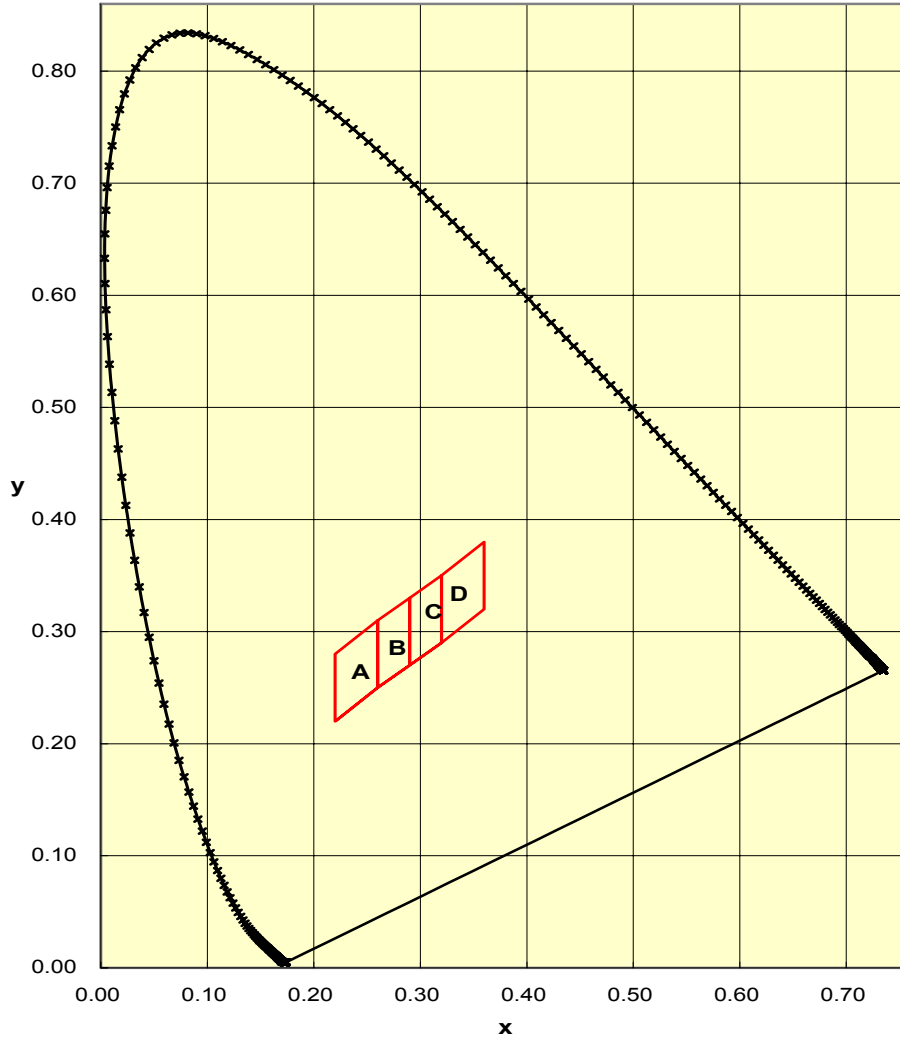
Hue Spec. Table

Hue Bin	Color bin limits at IF = 50mA				
	CIE 1931 Chromaticity coordinates				
A	x	0.220	0.220	0.260	0.260
	y	0.220	0.280	0.310	0.250
B	x	0.260	0.260	0.290	0.290
	y	0.250	0.310	0.330	0.270
C	x	0.290	0.290	0.320	0.320
	y	0.270	0.330	0.350	0.290
D	x	0.320	0.320	0.360	0.360
	y	0.290	0.350	0.380	0.320

Tolerance on each Hue (x, y) bin is +/- 0.02

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C.I.E. 1931 Chromaticity Diagram



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Typical Electrical / Optical Characteristics Curves (25°C Ambient Temperature Unless Otherwise Noted)

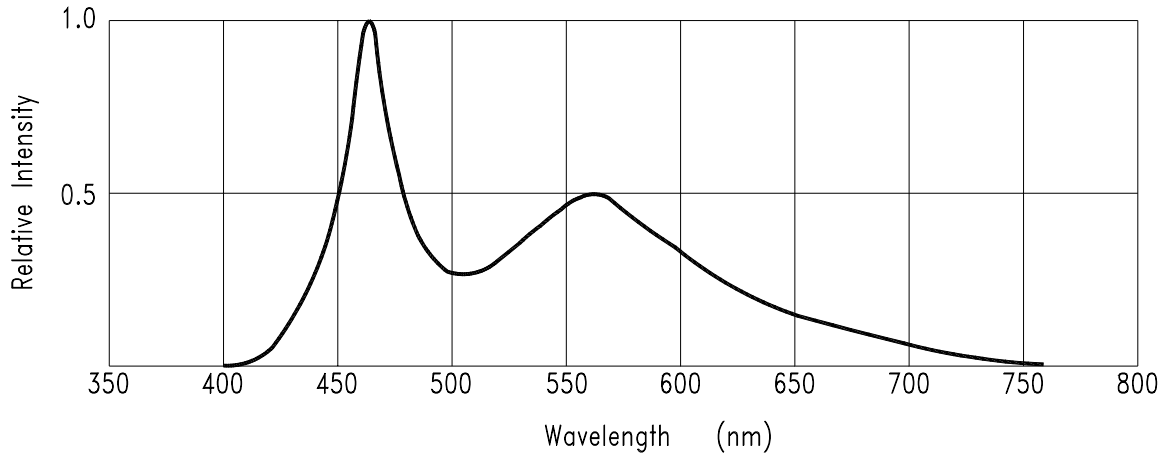


Fig.1 RELATIVE INTENSITY VS. WAVELENGTH

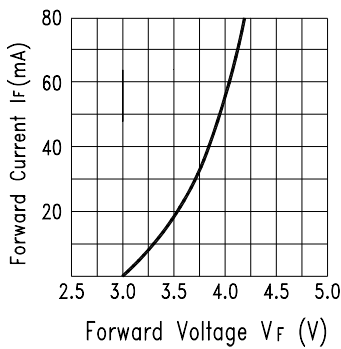


Fig.2 Forward Current vs. Forward Voltage

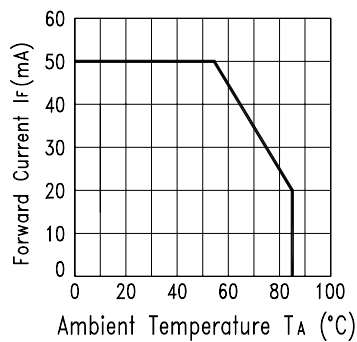


Fig.3 Forward Current Derating Curve

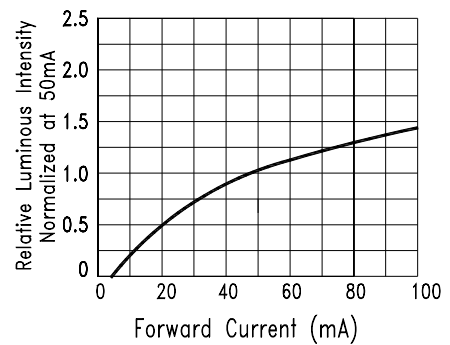


Fig.4 Relative Luminous Intensity vs. Forward Current

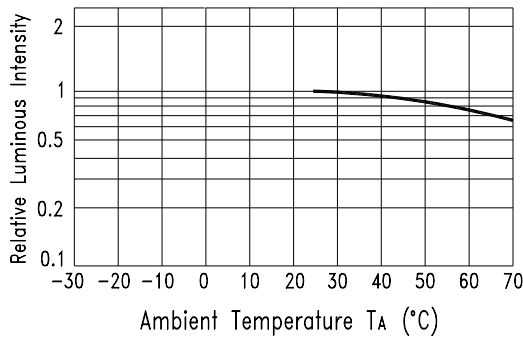


Fig.5 Luminous Intensity vs. Ambient Temperature

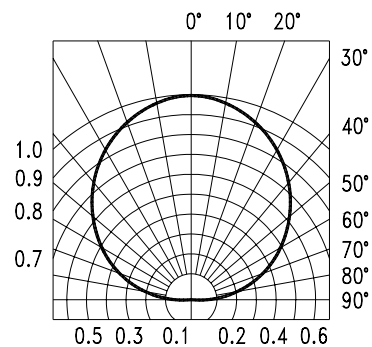


Fig.6 Spatial Distribution

User Guide

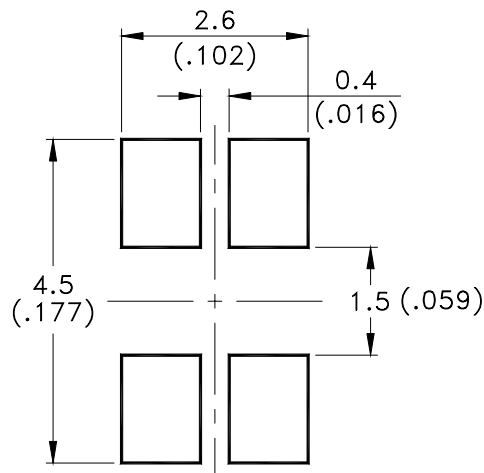
Cleaning

Do not use unspecified chemical liquid to clean LED they could harm the package.
 If cleaning is necessary, immerse the LED in ethyl alcohol or isopropyl alcohol at normal temperature for less than one minute.

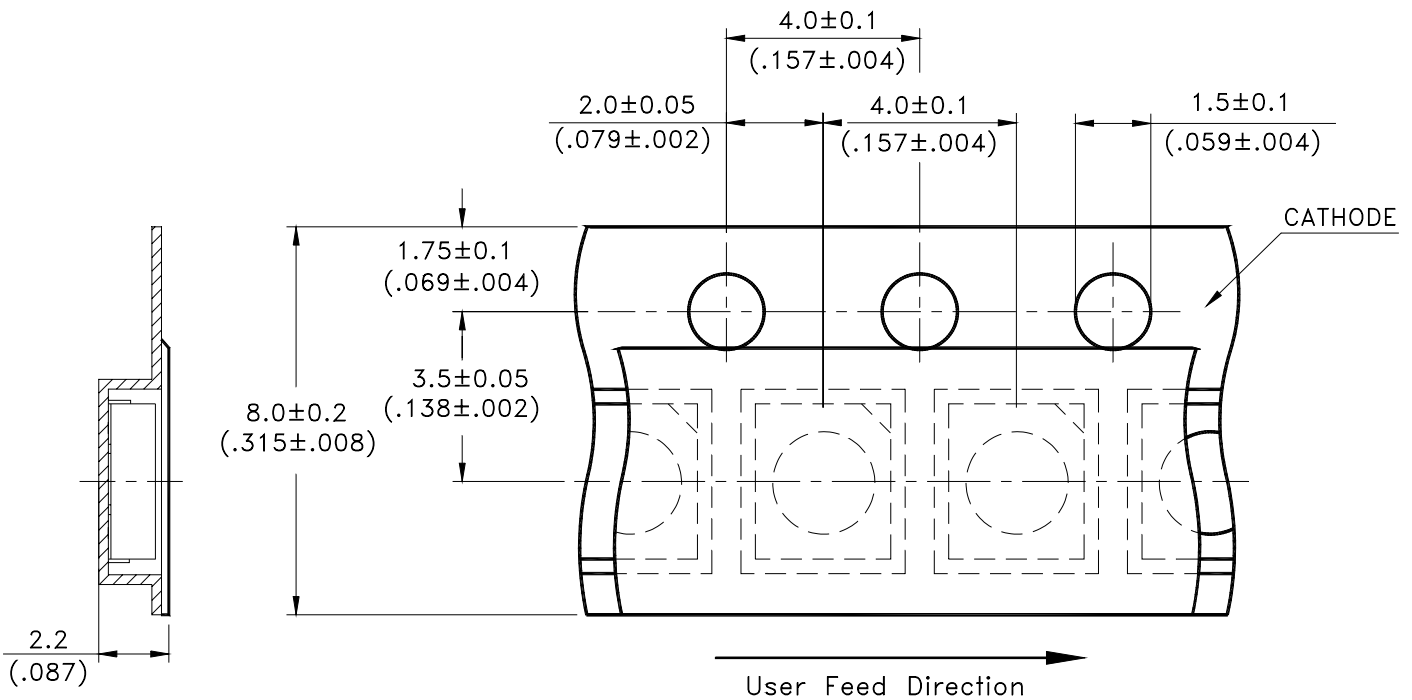
Recommend Printed Circuit Board Attachment Pad

Infrared / vapor phase

Reflow Soldering



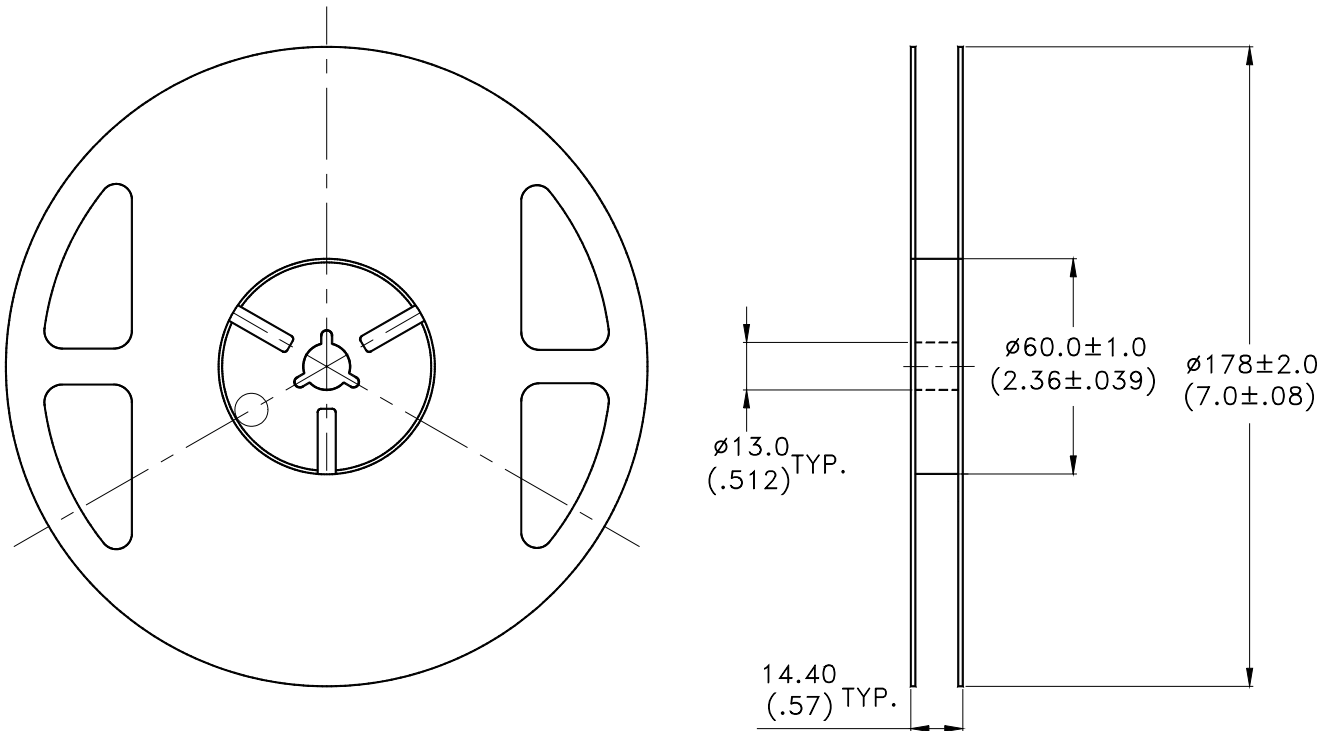
Package Dimensions of Tape



Note:

1. All dimensions are in millimeters (inches).

Property of Lite-On Only

Package Dimensions of Reel

Notes:

1. Empty component pockets sealed with top cover tape.
2. 7 inch reel-2000 pieces per reel.
3. Minimum packing quantity is 500 pieces for remainders.
4. The maximum number of consecutive missing lamps is two.
5. In accordance with EIA-481-1-B specifications.

CAUTIONS

1. Application

The LEDs described here are intended to be used for ordinary electronic equipment (such as office equipment, communication equipment and household applications). Consult Lite-on's Sales in advance for information on applications in which exceptional reliability is required, particularly when the failure or malfunction of the LEDs may directly jeopardize life or health (such as in aviation, transportation, traffic control equipment, medical and life support systems and safety devices).

2. Storage

The storage ambient for the LEDs should not exceed 85°C temperature or 60% relative humidity. It is recommended that LEDs out of their original packaging are IR-reflowed within one week. For extended storage out of their original packaging, it is recommended that the LEDs be stored in a sealed container with appropriate desiccant, or in desiccators with nitrogen ambient. LEDs stored out of their original packaging for more than a week should be baked at about 60 deg C for at least 24 hours before solder assembly.

3. Cleaning

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED if necessary.

4. Soldering

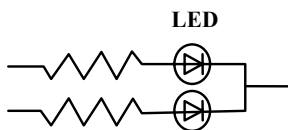
Recommended soldering conditions:

Reflow soldering		Wave Soldering		Soldering iron	
Pre-heat	120~150°C	Pre-heat	100°C Max.	Temperature	300°C Max.
Pre-heat time	120 sec. Max.	Pre-heat time	60 sec. Max.	Soldering time	3 sec. Max.
Peak Temp.	260°C Max.	Solder wave	260°C Max.		(one time only)
Soldering time	30 sec. Max.	Soldering time	10 sec. Max.		

5. Drive Method

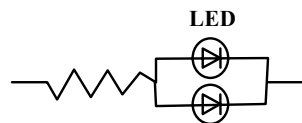
An LED is a current-operated device. In order to ensure intensity uniformity on multiple LEDs connected in parallel in an application, it is recommended that a current limiting resistor be incorporated in the drive circuit, in series with each LED as shown in Circuit A below.

Circuit model A



(A) Recommended circuit.

Circuit model B



(B) The brightness of each LED might appear different due to the differences in the I-V characteristics of those LEDs.

6. ESD (Electrostatic Discharge)

Static Electricity or power surge will damage the LED.

Suggestions to prevent ESD damage:

- Use of a conductive wrist band or anti-electrostatic glove when handling these LEDs.
- All devices, equipment, and machinery must be properly grounded.
- Work tables, storage racks, etc. should be properly grounded.
- Use ion blower to neutralize the static charge which might have built up on surface of the LED's plastic lens as a result of friction between LEDs during storage and handling.

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ESD-damaged LEDs will exhibit abnormal characteristics such as high reverse leakage current, low forward voltage, or “no lightup” at low currents.

To verify for ESD damage, check for “light up” and Vf of the suspect LEDs at low currents.

The Vf of “good” LEDs should be $>2.0V@0.1mA$ for InGaN product and $>1.4V@0.1mA$ for AlInGaP product.

7. Reliability Test

Classification	Test Item	Test Condition	Reference Standard
Endurance Test	Operation Life	Ta= Under Room Temperature As Per Data Sheet Maximum Rating *Test Time= 1000HRS (-24HRS,+72HRS)*@50mA.	MIL-STD-750D:1026 MIL-STD-883D:1005 JIS C 7021:B-1
	High Temperature High Humidity Storage	IR-Reflow In-Board, 2 Times Ta= 65±5°C, RH= 90~95% *Test Time= 240HRS±2HRS	MIL-STD-202F:103B JIS C 7021:B-11
	High Temperature Storage	Ta= 105±5°C *Test Time= 1000HRS (-24HRS,+72HRS)	MIL-STD-883D:1008 JIS C 7021:B-10
	Low Temperature Storage	Ta= -55±5°C *Test Time=1000HRS (-24HRS,+72HRS)	JIS C 7021:B-12
Environmental Test	Temperature Cycling	105°C ~ 25°C ~ -55°C ~ 25°C 30mins 5mins 30mins 5mins 10 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1010 JIS C 7021:A-4
	Thermal Shock	IR-Reflow In-Board, 2 Times 85 ± 5°C ~ -40°C ± 5°C 10mins 10mins 100 Cycles	MIL-STD-202F:107D MIL-STD-750D:1051 MIL-STD-883D:1011
	IR-Reflow	Ramp-up rate(217°C to Peak) +3°C/ second max Temp. maintain at 175(±25)°C 180 seconds max Temp. maintain above 217°C 60-150 seconds Peak temperature range 260°C+0/-5°C Time within 5°C of actual Peak Temperature (tp) 20-40 seconds Ramp-down rate +6°C/second max	MIL-STD-750D:2031.2 J-STD-020B
	Solderability	T.sol= 235 ± 5°C Immersion time 2±0.5 sec Immersion rate 25±2.5 mm/sec Coverage ≥95% of the dipped surface	MIL-STD-202F:208D MIL-STD-750D:2026 MIL-STD-883D:2003 IEC 68 Part 2-20 JIS C 7021:A-2

8. Others

The appearance and specifications of the product may be modified for improvement without prior notice.

9. Quality Guarantee

LiteOn guarantee DPPM level of failure function is smaller and equal to 50 DPPM.

(Based on 100k usage)

10. Suggested Checking List

Training and Certification

1. Everyone working in a static-safe area is ESD-certified?
2. Training records kept and re-certification dates monitored?

Static-Safe Workstation & Work Areas

1. Static-safe workstation or work-areas have ESD signs?
2. All surfaces and objects at all static-safe workstation and within 1 ft measure less than 100V?
3. All ionizer activated, positioned towards the units?
4. Each work surface mats grounding is good?

Personnel Grounding

1. Every person (including visitors) handling ESD sensitive (ESDS) items wear wrist strap, heel strap or conductive shoes with conductive flooring?
2. If conductive footwear used, conductive flooring also present where operator stand or walk?
3. Garments, hairs or anything closer than 1 ft to ESD items measure less than 100V*?
4. Every wrist strap or heel strap/conductive shoes checked daily and result recorded for all DLs?
5. All wrist strap or heel strap checkers calibration up to date?

Note: *50V for Blue LED.

Device Handling

1. Every ESDS items identified by EIA-471 labels on item or packaging?
2. All ESDS items completely inside properly closed static-shielding containers when not at static-safe workstation?
3. No static charge generators (e.g. plastics) inside shielding containers with ESDS items?
4. All flexible conductive and dissipative package materials inspected before reuse or recycle?

Others

1. Audit result reported to entity ESD control coordinator?
2. Corrective action from previous audits completed?
3. Are audit records complete and on file?